



# APPROVAL SHEET

Approval Specification	Customer's Approval Certificate
<p><b>TO:</b></p> <p><b>Part No.:</b></p> <p><b>Customer's Part No.:</b></p>	<p>Please return this copy as a certification of your approval</p> <p><b>Checked &amp; Approved by:</b></p> <p><b>Date:</b></p>

## BEIJING ZHONGXUN SIFANG SCIENCE & TECHNOLOGY CO.,LTD.

Tel: +86-010-62968745  
 Fax: +86-010-62973654  
 E-mail: [bjzxsf@bjzxsf.net](mailto:bjzxsf@bjzxsf.net)  
 Website: <http://www.bjzxsf.net>  
 Add: NO.7 NieGeZhuang Rd,SuJiaTuo Town,  
 HaiDian District,Beijing,P.R.China

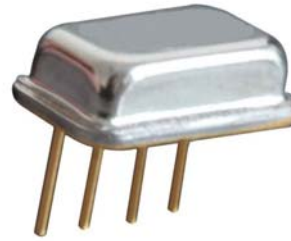


Part No.	:	SDL5103
Pages	:	4
Date	:	2013/5/30
Revision	:	1.0

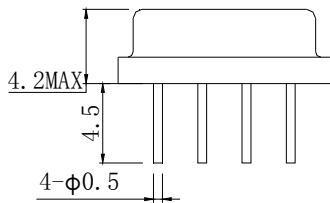
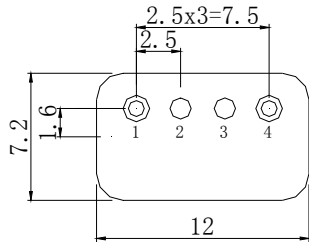
<b>Prepared by:</b>	郑宝琴
<b>Checked by:</b>	
<b>Approved by:</b>	

**Features**

- RoHS compatible
- Package size 12.0x7.20x4.20mm<sup>3</sup>
- Package Code SC04-01
- Electrostatic Sensitive Device(ESD)



**Package Dimensions (Unit: mm)**



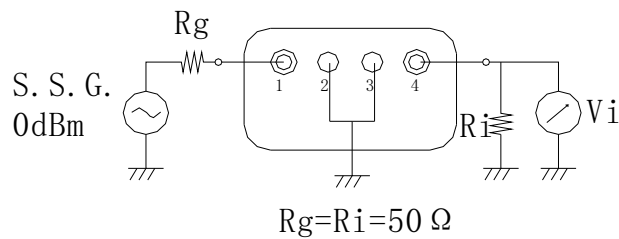
**Pin Configuration**

Pin No.	Description
1	Input
4	Output
2,3	Ground

**Marking Description**

<b>S</b>	Trademark
<b>DL</b>	SAW Delay Line
<b>5103</b>	Part Number
●	Pin 1
<b>YYWW</b>	Year Code & Week Code

**Test Circuit**



**Performance**

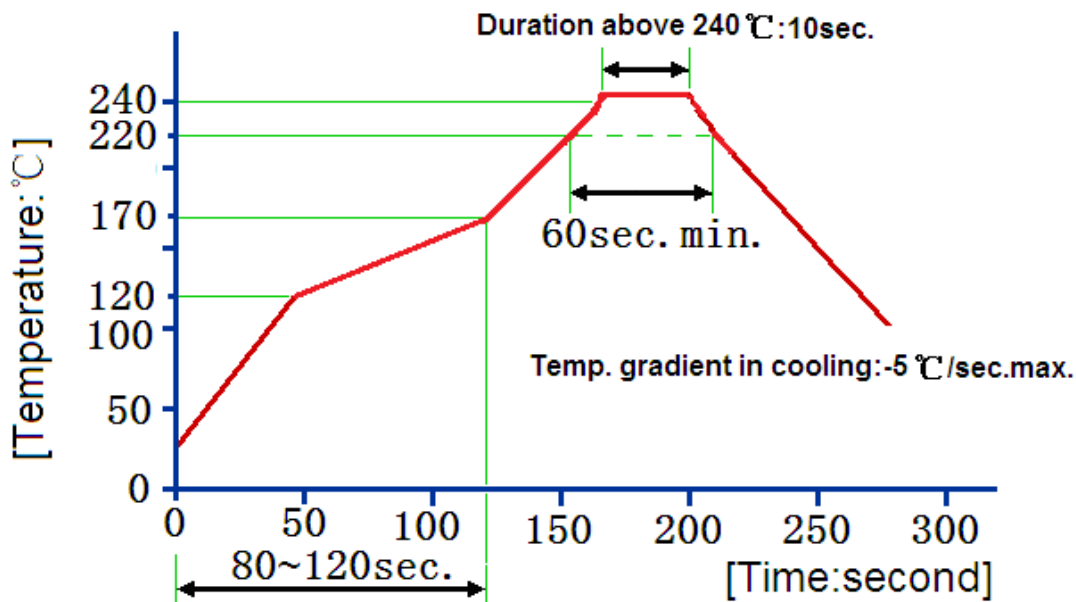
**Maximum Rating**

Item		Value	Unit
DC Voltage	V <sub>DC</sub>	3	V
Operation Temperature	T	-20 ~ +60	°C
Storage Temperature	T <sub>stg</sub>	-55 ~ +125	°C
RF Power Dissipation	P	10	dBm



4	Vibration Fatigue	Frequency of vibration: 10~55Hz Directions: X,Y and Z	Amplitude:1.5mm Duration: 2h
5	Drop Test	Cycle time: 10 times	Height: 1.0m
6	Solder Ability Test	Temperature: 245°C±5°C Depth: DIP--2/3 , SMD--1/5	Duration: 3.0s--5.0s
7	Resistance to Soldering Heat	(1)Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration: 10±1s (2)Temperature of Soldering Iron: 350°C±10°C , Duration: 3~4s , Recovery time : 2 ± 0.5h	

### Recommended Reflow Soldering Diagram



Reflow cycles: 3 cycles max.

### Notes

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.